

1.本站收集的数据手册和产品资料都来自互联网,版权归原作者所有。如读者和版权方有任 何异议请及时告之,我们将妥善解决。

本站提供的中文数据手册是英文数据手册的中文翻译,其目的是协助用户阅读,该译文无法自动跟随原稿更新,同时也可能存在翻译上的不当。建议读者以英文原稿为参考以便获得更精准的信息。

3.本站提供的产品资料,来自厂商的技术支持或者使用者的心得体会等,其内容可能存在描 叙上的差异,建议读者做出适当判断。

4.如需与我们联系,请发邮件到marketing@iczoom.com,主题请标有"数据手册"字样。

Read Statement

1. The datasheets and other product information on the site are all from network reference or other public materials, and the copyright belongs to the original author and original published source. If readers and copyright owners have any objections, please contact us and we will deal with it in a timely manner.

2. The Chinese datasheets provided on the website is a Chinese translation of the English datasheets. Its purpose is for reader's learning exchange only and do not involve commercial purposes. The translation cannot be automatically updated with the original manuscript, and there may also be improper translations. Readers are advised to use the English manuscript as a reference for more accurate information.

3. All product information provided on the website refer to solutions from manufacturers' technical support or users the contents may have differences in description, and readers are advised to take the original article as the standard.

4. If you have any questions, please contact us at marketing@iczoom.com and mark the subject with "Datasheets".

Logic level TOPFET

BUK150-50DL

DESCRIPTION

Monolithic temperature and overload protected logic level power MOSFET in TOPFET2 technology assembled in a 3 pin plastic package.

APPLICATIONS

General purpose switch for driving

- lamps
- motors .
- solenoids
- heaters

in automotive systems and other applications.

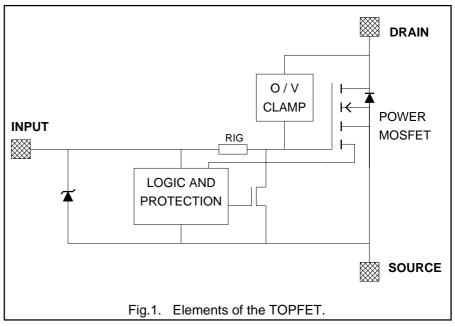
FEATURES

- TrenchMOS output stage
- Current limiting
- Overload protection •
- .
- Overtemperature protection Protection latched reset by input •
- 5 V logic compatible input level Control of output stage and . supply of overload protection circuits derived from input
- Low operating input current permits direct drive by micro-controller
- ESD protection on all pins
- Overvoltage clamping for turn • off of inductive loads

QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	UNIT
V_{DS} I_{D} P_{D} T_{j} $R_{DS(ON)}$ I_{ISL}	PARAMETER Continuous drain source voltage Continuous drain current Total power dissipation Continuous junction temperature Drain-source on-state resistance Input supply current V _{IS} = 5 V		V Α Ψ°C mΩ μΑ

FUNCTIONAL BLOCK DIAGRAM

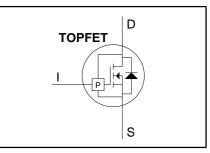


PINNING - SOT226

PIN	DESCRIPTION
1	input
2	drain
3	source
tab	drain



SYMBOL



23 1

LIMITING VALUES

Limiting values in accordance with the Absolute Maximum Rating System (IEC 134)

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{DS}	Continuous drain source voltage ¹		-	50	V
I _D	Continuous drain current	$V_{IS} = 5 V; T_{mb} = 25^{\circ}C$	-	self -	А
				limited	
I _D	Continuous drain current	V _{IS} = 5 V; T _{mb} ≤121°C	-	20	A
I,	Continuous input current		-5	5	mA
I _{IRM}	Repetitive peak input current	$\delta \le 0.1$, tp = 300 μ s	-50	50	mA
P _D	Total power dissipation	$T_{mb} \le 25^{\circ}C$	-	90	W
T _{stg}	Storage temperature		-55	175	°C
T _j	Continuous junction temperature ²	normal operation	-	150	°C
T_{sold}	Case temperature	during soldering	-	260	°C

ESD LIMITING VALUE

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _c	Electrostatic discharge capacitor voltage	Human body model; C = 250 pF; R = 1.5 k Ω	-	2	kV

OVERVOLTAGE CLAMPING LIMITING VALUES

At a drain source voltage above 50 V the power MOSFET is actively turned on to clamp overvoltage transients.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
E _{DSM} E _{DRM}	Inductive load turn-off Non-repetitive clamping energy Repetitive clamping energy	$\begin{split} I_{DM} &= 20 \text{ A}; V_{DD} \leq 20 \text{ V} \\ T_{mb} \leq 25 ^{\circ}\text{C} \\ T_{mb} \leq 95 ^{\circ}\text{C}; f = 250 \text{ Hz} \end{split}$	-	350 45	mJ mJ

OVERLOAD PROTECTION LIMITING VALUE

With an adequate protection supply provided via the input pin, TOPFET can protect itself from two types of overload - overtemperature and short circuit load.

SYMBOL	PARAMETER	REQUIRED CONDITION	MIN.	MAX.	UNIT
V _{DS}	Drain source voltage ³	$4~V \leq V_{IS} \leq 5.5~V$	0	35	V

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
R _{th j-mb}	Thermal resistance Junction to mounting base	-	-	1.25	1.39	K/W
R _{th j-a}	Junction to ambient		-	50	-	K/W

¹ Prior to the onset of overvoltage clamping. For voltages above this value, safe operation is limited by the overvoltage clamping energy.

 $[\]mathbf{2}$ A higher T_j is allowed as an overload condition but at the threshold $T_{j(TO)}$ the over temperature trip operates to protect the switch.

³ All control logic and protection functions are disabled during conduction of the source drain diode.

OUTPUT CHARACTERISTICS

Limits are for -40 $^{\circ}C \leq T_{mb} \leq 150 \,^{\circ}C$; typicals are for T_{mb} = 25 $^{\circ}C$ unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
	Off-state	$V_{IS} = 0 V$				
V _{(CL)DSS}	Drain-source clamping voltage	I _D = 10 mA	50	-	-	V
		$I_{\text{DM}} = 4 \text{ A}; t_p \le 300 \mu\text{s}; \delta \le 0.01$	50	60	70	V
I _{DSS}	Drain source leakage current	$V_{DS} = 40 V$	-	-	100	μA
		$T_{mb} = 25^{\circ}C$	-	0.1	10	μA
	On-state	$V_{\text{IS}} \geq 4.4 \text{ V}; \ t_{\text{p}} \leq 300 \ \mu\text{s}; \ \delta \leq 0.01$				
R _{DS(ON)}	Drain-source resistance	I _{DM} = 10 A	-	-	52	mΩ
		$T_{mb} = 25^{\circ}C$	-	22	28	mΩ

OVERLOAD CHARACTERISTICS

 V_{IS} = 5 V; T_{mb} = 25°C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
	Short circuit load					
I _D	Drain current limiting	V _{DS} = 13 V	28.5	43	57	Α
		$4.4 V \le V_{IS} \le 5.5 V;$ -40°C ≤ T _{mb} ≤ 150°C	21	-	65	A
	Overload protection					
${\sf P}_{{\sf D}({\sf TO})}$ ${\sf T}_{{\sf DSC}}$	Overload power threshold Characteristic time	device trips if $P_D > P_{D(TO)}$ which determines trip time ¹	75 200	185 380	250 600	W μs
	Overtemperature protection					
$T_{j(TO)}$	Threshold junction temperature ²		150	170	-	°C

¹ Trip time $t_{d sc}$ varies with overload dissipation P_D according to the formula $t_{d sc} \approx T_{DSC} / ln[P_D / P_{D(TO)}]$.

² This is independent of the dV/dt of input voltage V_{IS} .

Logic level TOPFET

INPUT CHARACTERISTICS

The supply for the logic and overload protection is taken from the input. Limits are for -40°C \leq T_{mb} \leq 150°C; typicals are for T_{mb} = 25°C unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS		MIN.	TYP.	MAX.	UNIT
V _{IS(TO)}	Input threshold voltage	$V_{DS} = 5 V; I_{D} = 1 mA$	T _{mb} = 25°C	0.6 1.1	- 1.6	2.4 2.1	V V
I _{IS}	Input supply current	normal operation;	V _{IS} = 5 V V _{IS} = 4 V	100 80	220 195	400 330	μΑ μΑ
I _{ISL}	Input supply current	protection latched;	V _{IS} = 5 V V _{IS} = 3 V	200 130	400 250	650 430	μΑ μΑ
V _{ISR}	Protection reset voltage ¹	reset time $t_r \ge 100 \ \mu s$		1.5	2	2.9	V
t _{ir}	Latch reset time	$V_{IS1} = 5 V, V_{IS2} < 1 V$		10	40	100	μs
V _{(CL)IS}	Input clamping voltage	l ₁ = 1.5 mA		5.5	-	8.5	V
R _{IG}	Input series resistance ² to gate of power MOSFET		$T_{mb} = 25^{\circ}C$	-	33	-	kΩ

SWITCHING CHARACTERISTICS

 T_{mb} = 25°C; V_{DD} = 13 V; resistive load R_L = 4 Ω . Refer to waveform figure and test circuit.

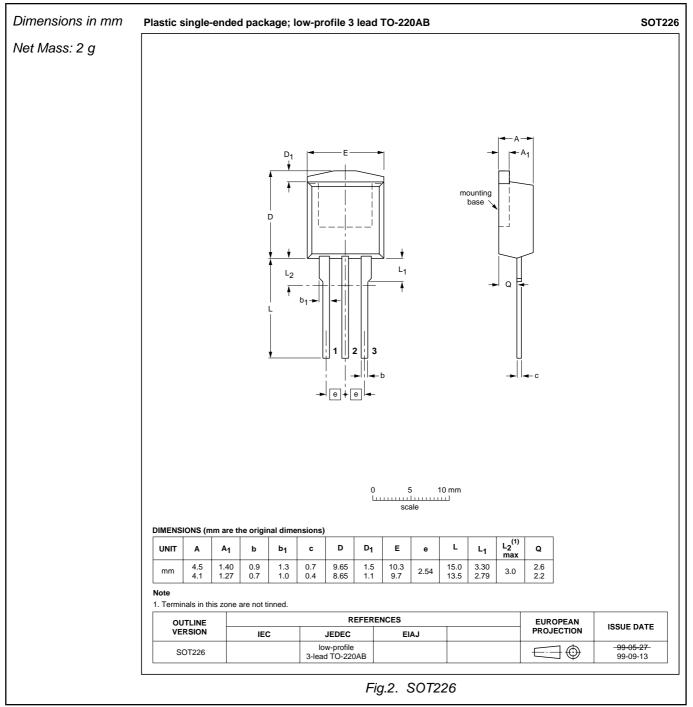
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
t _{d on}	Turn-on delay time	$V_{IS} = 5 V$	-	25	50	μs
t,	Rise time		-	50	100	μs
t _{d off}	Turn-off delay time	$V_{IS} = 0 V$	-	60	120	μs
t _f	Fall time		-	50	100	μs

¹ The input voltage below which the overload protection circuits will be reset.

² Not directly measureable from device terminals.

Logic level TOPFET

MECHANICAL DATA



Notes

Refer to mounting instructions for SOT226 package.
 Epoxy meets UL94 V0 at 1/8".

BUK150-50DL

DEFINITIONS

DATA SHEET STATUS						
PRODUCT STATUS ²	DEFINITIONS					
Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice					
Qualification This data sheet contains data from the preliminary specification Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification notice, in ordere to improve the design and supply the best poproduct						
Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Changes will be communicated according to the Customer Product/Process Change Notification (CPCN) procedure SNW-SQ-650A					
	PRODUCT STATUS ² Development Qualification					

Limiting values

Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information

Where application information is given, it is advisory and does not form part of the specification.

© Philips Electronics N.V. 2001

All rights are reserved. Reproduction in whole or in part is prohibited without the prior written consent of the copyright owner.

The information presented in this document does not form part of any quotation or contract, it is believed to be accurate and reliable and may be changed without notice. No liability will be accepted by the publisher for any consequence of its use. Publication thereof does not convey nor imply any license under patent or other industrial or intellectual property rights.

LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices or systems where malfunction of these products can be reasonably expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.

¹ Please consult the most recently issued datasheet before initiating or completing a design.

² The product status of the device(s) described in this datasheet may have changed since this datasheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.